



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUZ40N08S5N100	Issued	11. April 2021
MA#	MA005346314		
Package	PG-TSDSON-8-32	Weight*	35.62 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.566	1.59	1.59	15889	15889
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		87	
	non noble metal	zinc	7440-66-6	0.012	0.03		349	
	non noble metal	iron	7439-89-6	0.249	0.70		6985	
	non noble metal	copper	7440-50-8	10.102	28.36	29.10	283636	291057
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	782	782
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1032	
	plastics	epoxy resin	-	1.892	5.31		53126	
	inorganic material	silicondioxide	60676-86-0	16.442	46.17	51.58	461629	515787
leadfinish	non noble metal	tin	7440-31-5	0.400	1.12	1.12	11238	11238
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2404	2404
solder	non noble metal	tin	7440-31-5	0.016	0.05		453	
	noble metal	silver	7440-22-4	0.020	0.06		567	
	non noble metal	lead	7439-92-1	0.771	2.17	2.28	21651	22671
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.073	0.20		2045	
	non noble metal	copper	7440-50-8	2.958	8.30	8.51	83038	85211
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			16	
	non noble metal	zinc	7440-66-6	0.002	0.01		66	
	non noble metal	iron	7439-89-6	0.047	0.13		1319	
	non noble metal	copper	7440-50-8	1.908	5.36	5.50	53560	54961
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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